

ABSTRACT OF DISCLOSURE

A method of fabricating an ink-jet print head includes at least one process of forming an ink feeding port. The ink feeding port forming process comprises fixing a wafer to a stage in a chamber, and processing the ink feeding port to a desired depth in the wafer using a liquid-jet guided laser. In addition, the method of fabricating the ink-jet print head includes a process of dicing a wafer in order to cut the wafer in the form of chips. The wafer dicing process comprises fixing the wafer to a stage in a chamber, and dicing the wafer using a liquid-jet guided laser. According to the present invention, the liquid-jet guided laser that combines laser and a micro liquid-jet is used when forming an ink-feeding port of a print head and/or when dicing the wafer formed with a plurality of print heads, whereby it is possible to achieve effects that a thermal damage of the print heads can be prevented, process costs can be saved, and a process time can be reduced.